

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

30.03.2026

WURTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	μm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	306		2	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		3	
		35	L2		
B-STD-FR4-ML-0.711mm-035+035-TG150-HF...	50203135	710		4	
		35	L3		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	306		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7	

Thickness after Pressing

B00: 1440 μm Tol+: 155 μm Tol-: 155 μm Dmax: 1595 μm Dmin: 1285 μm

Thickness over all

0 μm Tol+: 0 μm Tol-: 0 μm Dmax: 0 μm Dmin: 0 μm

Demand for customer

Thickness (D): 1550 μm Tol+: 155 μm Tol-: 155 μm Dmax: 1705 μm Dmin: 1395 μm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 1428 μm

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